

ABSTRACT

Compositions having a curable unsaturated compound, an adhesion promoter and curing agent which have a peak exotherm of less than 50°C are disclosed. The compositions when cured are flexible bioadhesives which are also disclosed. Non-curable diluents can be included in the compositions. Flexible bioadhesives formed on biological structures and having low peak exotherms upon curing of curable compositions to form the flexible bioadhesives are disclosed. Compositions having a curable unsaturated compound and a curing agent and a peak exotherm of less than 50°C are included in the invention.

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